



DOCKET NO.: 209211US0

**IN THE UNITED STATES PATENT & TRADEMARK OFFICE**

IN RE APPLICATION OF : :

Yukihiko SHIRAKAWA : GROUP ART UNIT: 2879

SERIAL NO.: 09/866,732 : :

FILED: May 30, 2001 : EXAMINER: HARPER, H.

FOR: THIN-FILM EL DEVICE, AND ITS FABRICATION PROCESS

RECEIVED  
JUL -3 2003  
TECHNOLOGY CENTER 2800

#14B Amot  
J. Brunson  
7/17/03

**AMENDMENT AND REQUEST FOR RECONSIDERATION**

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

In response to the Office Action dated March 31, 2003, please reconsider the application in view of the following amendment and remarks.

**IN THE CLAIMS**

Please add the following new Claims.

6. (New) The thin-film EL device according to Claim 1, wherein said electrically insulating substrate maintains a given heat-resistant strength without contaminating said patterned electrode layer and said dielectric layer.

7. (New) The thin-film EL device according to Claim 1, wherein said electrically insulating substrate is selected from the group consisting of alumina ( $Al_2O_3$ ), quartz glass ( $SiO_2$ ), magnesia ( $MgO$ ), forsterite ( $2MgO \cdot SiO_2$ ), steatite ( $MgO \cdot SiO_2$ ), mullite ( $3Al_2O_3 \cdot 2SiO_2$ ), beryllia ( $BeO$ ), zirconia ( $ZrO_2$ ), aluminum nitride ( $AlN$ ), silicon nitride ( $SiN$ ), silicon carbide ( $SiC$ ), crystallized glass, high heat-resistance glass, green sheet glass substrates and enameled metal substrates.